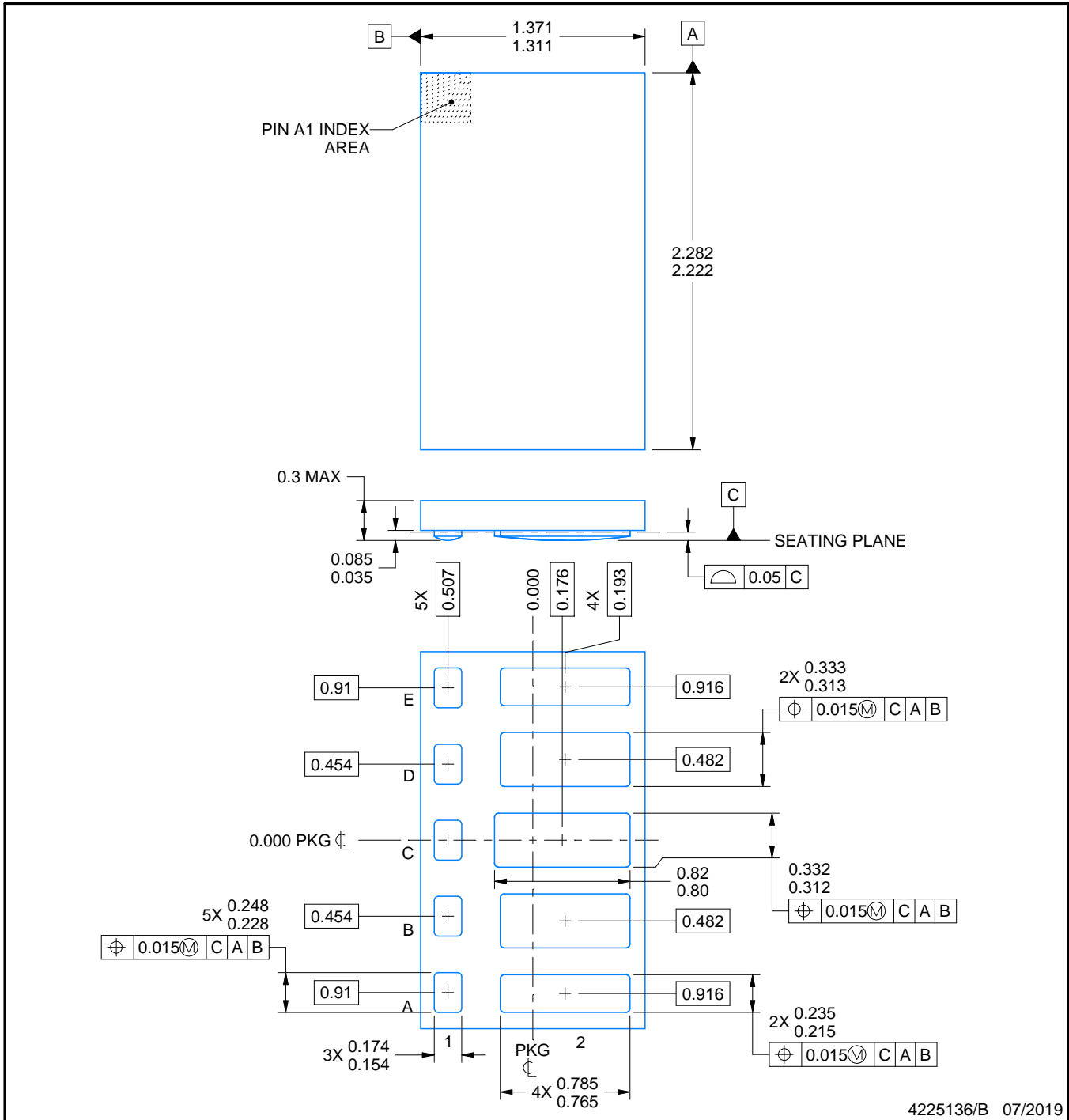


# PACKAGE OUTLINE

## YWC0010A

### PowerWCSPP - 0.3 mm max height

POWER CHIP SCALE PACKAGE



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#### NOTES:

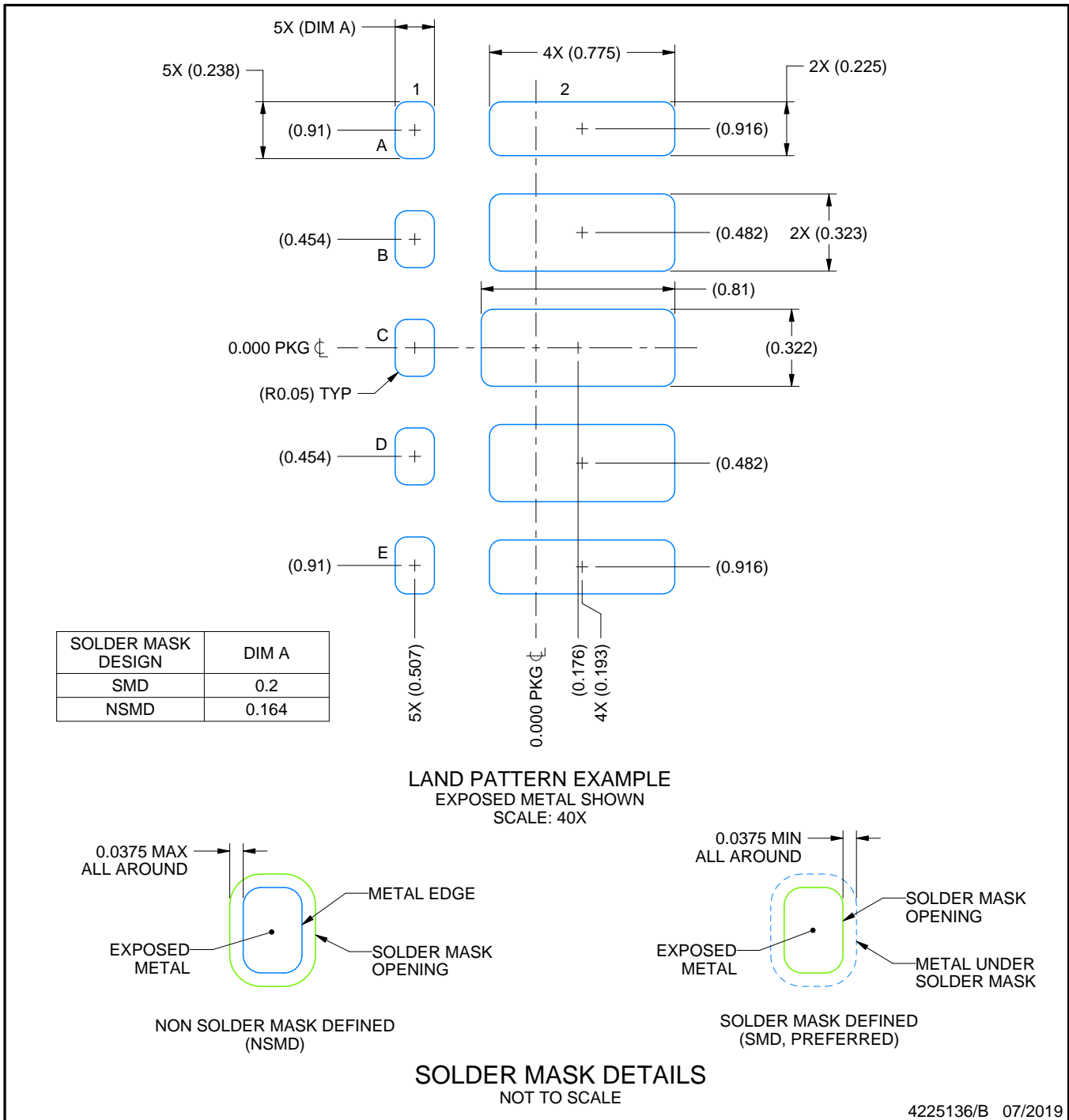
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

YWC0010A

PowerWCSP - 0.3 mm max height

POWER CHIP SCALE PACKAGE



NOTES: (continued)

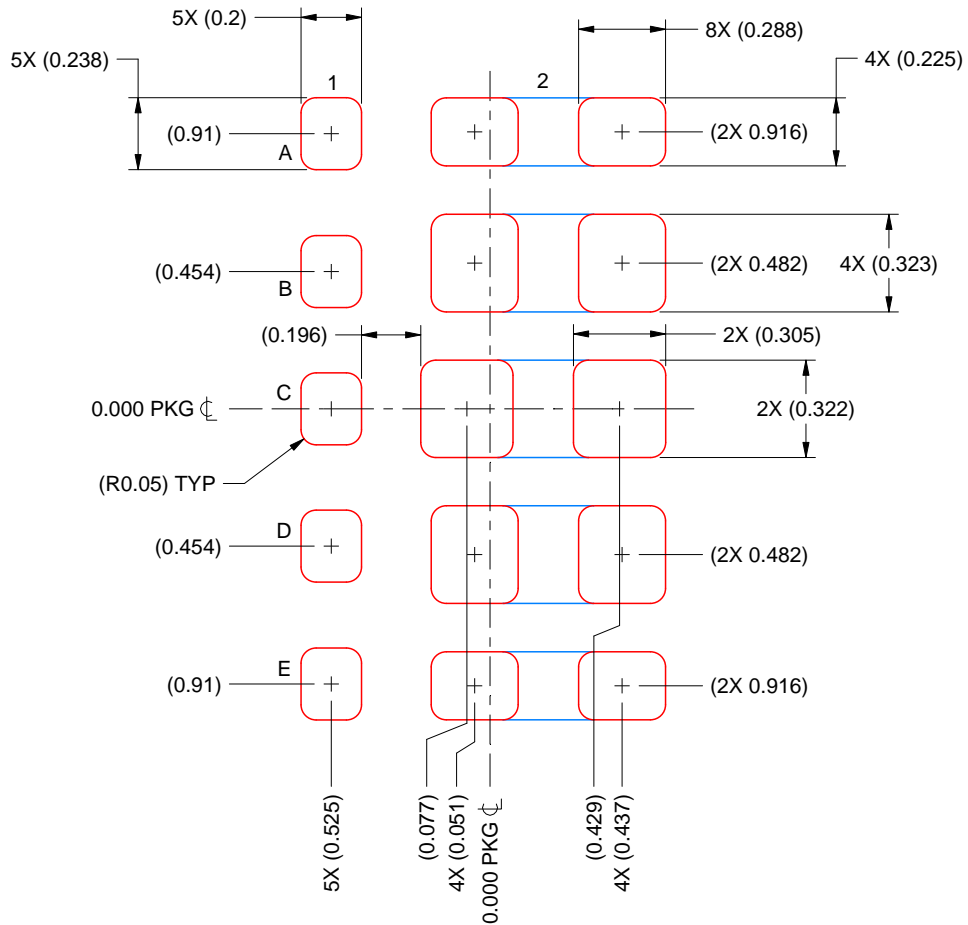
3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slue271](http://www.ti.com/lit/slue271)).

# EXAMPLE STENCIL DESIGN

YWC0010A

PowerWCSP - 0.3 mm max height

POWER CHIP SCALE PACKAGE



**SOLDER PASTE EXAMPLE**  
 BASED ON 0.075 mm THICK STENCIL

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
 PINS A2, B2, D2 & E2: 74%  
 PINS C2: 75%  
 SCALE: 40X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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